

Bienvenue chez O-Leading

O-Leading s'efforce d'être votre partenaire de solution unique dans la chaîne d'approvisionnement EMS, y compris la conception de PCB, la fabrication de PCB et l'assemblage de PCB (PCBA) .Nous fournissons certaines des technologies de PCB les plus avancées, y compris les PCB HDI, les PCB multicouches, les PCB rigides et flexibles Nous pouvons prendre en charge du prototype à virage rapide à la production moyenne et en masse. [PCB double face en Chine](#)

En général, nos clients mondiaux sont très impressionnés par nos services: réponse rapide, prix compétitif et engagement de qualité.

En regardant vers l'avenir, O-leader se concentrera sur l'innovation et le développement de la technologie de fabrication électronique comme toujours, et déploiera des efforts persistants sur le service unique PCB & PCBA pour fournir des services de première classe et créer plus de valeur pour nos clients. [Carte de circuit imprimé en Chine](#)

Détails rapides

Lieu d'origine	Guang dong, Chine (continentale)	Marque	O-leader
Matériel de base	FR-4, aluminium	Épaisseur de cuivre	0,5 oz-5 oz
Min. Taille du trou	0,2 mm	Min. Largeur de ligne	0,2 mm
Finition de surface	immersion or, OSP, sans plomb HASL	Épaisseur du panneau	0,1 à 5 mm
applicable à	led, téléphone portable, climatiseurs, machines à laver	personnage	PCB de contrôle industriel
certificats	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
poids	0,01 kg -5 kg	MOQ	10 pièces
Couleur	bleu, rouge, vert, noir.jaune	Min. Interligne	0,2 mm
Numéro de modèle	fabricant de pcba de banque de puissance	prix	0,1 \$ à 10 \$
type de desigh	exigence du client	type de desigh	exigence du client

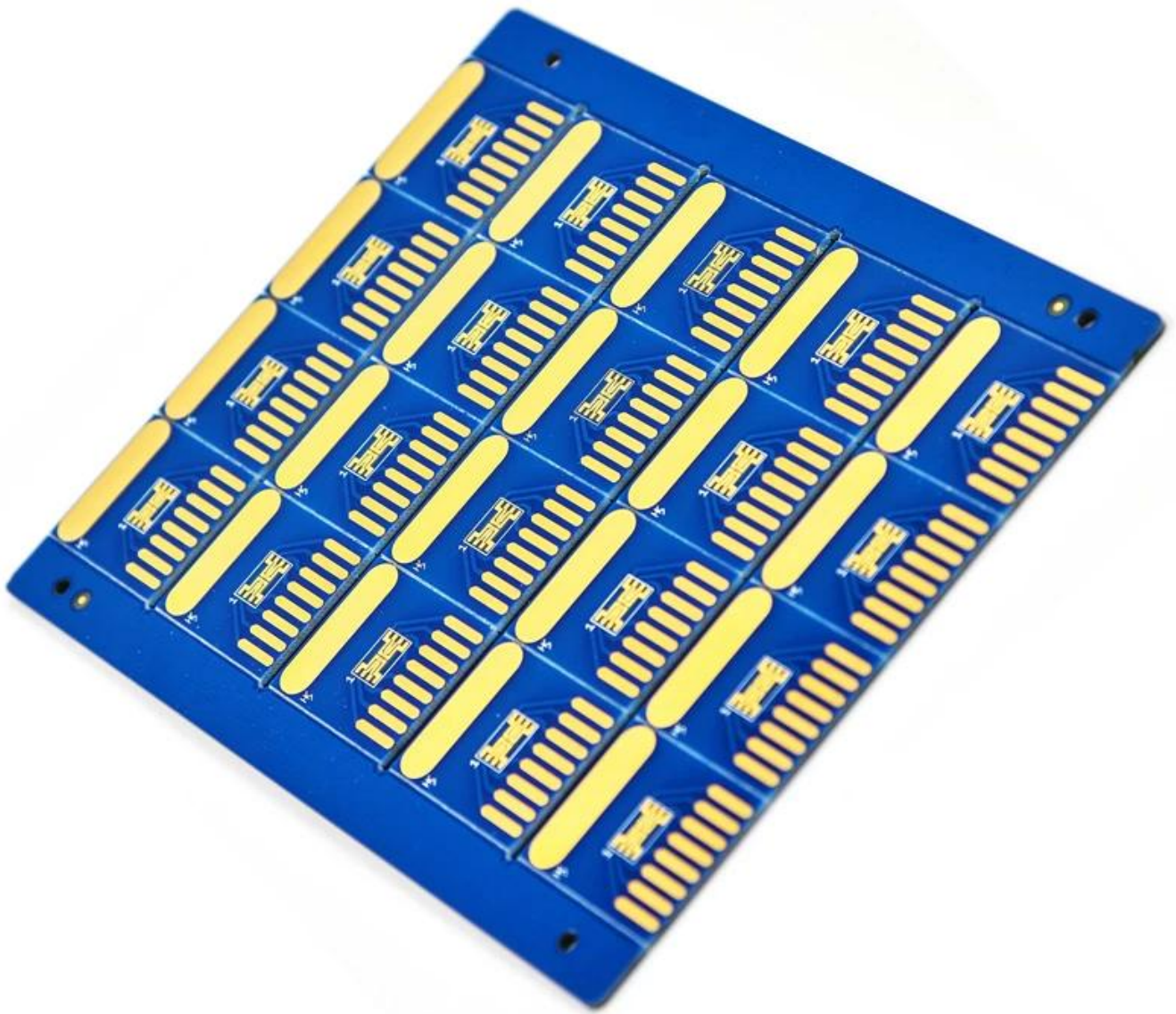
La capacité de production

16 ans de fabrication professionnelle de circuits imprimés OEM

article	2014		2015 ~ 2016		2017 ~ 2018	
	Le volume	Échantillon	Le volume	Échantillon	Le volume	Échantillon
Nombre de couches	32	42	38	44	42	48
Ligne min / espace (µm)	50/50	40/45	40/45	40/40	35/40	35/35
Trou de forage minimum diamètre (mm)	0,15	0,10	0,15	0,10	0,15	0,10

Ratio d'aspect de PTH	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1
N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Interconnexion de n'importe quelle couche	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Remplissage de plaque via	OUI	-	OUI	-	OUI	-
Min. épaisseur du noyau (à l'exclusion du cuivre) (µm)	50	40	40	30	40	30
Min. Diamètre de perçage laser (µm)	75	65	65	50	50	40
Via sur enterré trou / empilé via	OUI	-	OUI	-	OUI	-
Matériel	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
PCB de condensateur intégré	OUI	-	OUI	-	OUI	-
Processus de surface	HASL sans plomb, ENIG, OSP, Argent d'immersion, Étain d'immersion, Or flash, plaqué or, plaqué or dur sélectif, Masque de soudure pelable, encre carbone					

Société de circuits imprimés



Notre équipe



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Certifications





No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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*SOS Ship No.4, Jiaxing Industrial Park, No.42, Jiaxing Road, Jiangsu District, Shanghai, China 518129 | (86-755) 26328888 | (86-755) 83106190 | www.sgschina.com on
 in english: CN.Dongsheng@sas.com | (86-755) 26328888 | (86-755) 83106190 | www.sgschina.com

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No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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SIGS GROUP Technical Service Center
506 Stg. #2, Jiahe Industrial Park, No.430, Zhuang Road, Lingyuan District, Shenzhen, China 518129 | (86)-755-25202888 | (86)-755-85106190 | www.sigsgroup.com.cn
中國·深圳·龙岗区田面路430號莊園工業園SIGS技術服務中心 熱線：518129 | (86)-755-25202888 | (86)-755-85106190 | sigs.china@sigs.com

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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max					
	Min	Min			Area	Solder	Oper	Flame	Meets	C	
	mm(in)	Edge mm(in)			Diam	Limits	Temp	Class	UL796	T	
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Capacité du processus

Capacités de production de PCB

Nombre de couches: 1 couche-32 couches

Épaisseur de cuivre fini: 1 / 3oz-12oz

Largeur / espacement des lignes min. Interne: 3.0mil / 3.0mil

Largeur / espacement des lignes min externes: 4.0mil / 4.0mil

Rapport d'aspect max: 10: 1

Épaisseur du panneau: 0,2 mm à 5,0 mm

Taille maximale du panneau (pouces): 635 * 1500 mm

Taille minimale du trou percé: 4mil

Tolérance de trou Plated: +/- 3mil

Blind / Buried Vias (types All): OUI

Via remplissage (conducteur, non conducteur): OUI

Matériau de base: FR-4, FR-4High Tg.Halogen free material, Rogers, Aluminium base,Polyimide,

Cuivre lourd

Finitions de surface: HASL, OSP, ENIG, HAL-LF, Immersion silver,Étain d'immersion, doigts d'or, encre de carbone

Capacités de production SMT

Matériau PCB: FR-4, CEM-1, CEM-3, carte à base d'aluminium

Taille maximale du PCB: 510x460mm

Taille minimale du PCB: 50x50mm

Épaisseur du PCB: 0,5 mm à 4,5 mm

Épaisseur du panneau: 0,5-4 mm

Taille minimale des composants: 0201

Composant de taille de puce standard: 0603 et plus

Hauteur maximale des composants: 15 mm

Pas de plomb mini: 0,3 mm

Pas de balle BGA minimum: 0,4 mm

Précision de placement: +/- 0,03 mm